

# PATENT ABSTRACTS OF JAPAN

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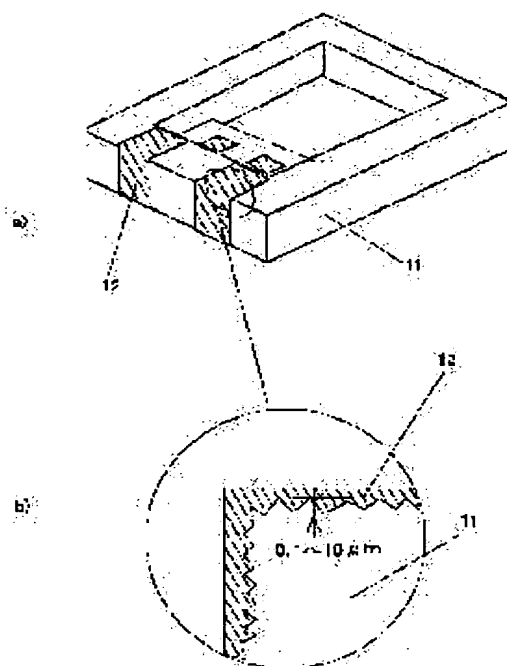
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## (54) RESIN MOLDING AND PRODUCTION OF RESIN MOLDING

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a resin molding capable of forming fine patterns and producing an inexpensive electron circuit structure and a process for producing this resin molding.

**SOLUTION:** The stage for directly laminating a metallic layer 12 on a resin 11 in the process for producing the resin molding directly laminated with the resin 11 consisting of a single material and the metallic layer 12 without the intervention of an adhesive layer consists of a stage for roughening the surface itself of the resin 11 to a surface roughness of  $\geq 0.1$  to  $\leq 10$  microns and a stage for footing the metallic layer 12 by direct electroless plating on the surface of the resin 11 roughened in this stage.



## LEGAL STATUS

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